© Copyright 2005, IPC	© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
				Form Type * Distribute					ials and Mfg Information					
Supplier Information														
Company name*		Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2025-09-12			
ntact Name Title - Contact				Phone - Contact*				Email - Contact*						
Product-Env-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title -			Fitle - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Number Mfr Item Name			Effective Date	Version		Manufacturing Site		Weight*	UOM	Unit Type	
	NTMTS	TMTSC1D5N08MC PTNG 80V in Cel industrial market		bu PQFN88 Dual Co	ool for	2025-09-12	5-09-12 PBB		PBB		319.28	mg	Each	
Manufacturing Proccess Information	on													
Terminal Plating / Grid Array Mate	rminal Plating / Grid Array Material Terminal Base Alloy		Alloy	J-STD-020 MSL Rati	ing	Peak Proc	ess Body T	emperatu	re Max Time at Peak	Tempera	ture Numl	per of Reflow Cy	les	
Matte Tin (Sn) - annealed CU Alloy		1	1		260		С	30	seco	nds 3				
Comments														
level 1 - maximum time at peak temperature	e during sol	dering is 10-3	0 seconds											
For more information regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl opthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	86.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.1033	mg
			Supplier	Iron (Fe)	7439-89-6		2.0234	mg
			Supplier	Copper (Cu)	7440-50-8		83.9475	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0258	mg
Die	6.27	mg	Supplier	Silicon (Si)	7440-21-3		6.27	mg
Die Attach Solder	15.3	mg	Supplier	Silver (Ag)	7440-22-4		0.3825	mg
			А	Lead (Pb)	7439-92-1	7a	14.1525	mg
			Supplier	Tin (Sn)	7440-31-5		0.765	mg
Lead Frame	103.2	mg	Supplier	Silver (Ag)	7440-22-4		0.0826	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1238	mg
			Supplier	Iron (Fe)	7439-89-6		2.4252	mg
			Supplier	Copper (Cu)	7440-50-8		100.5374	mg
			Supplier	Phosphorus (P)	7723-14-0		0.031	mg
Mold Compound-Black	103.88	mg		Epoxy resin	proprietary data		5.194	mg
			Supplier	Phenolic Resin	Proprietary Data		2.3892	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4155	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.3892	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		88.298	mg
Plating	4.48	mg	Supplier	Tin (Sn)	7440-31-5		4.48	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg